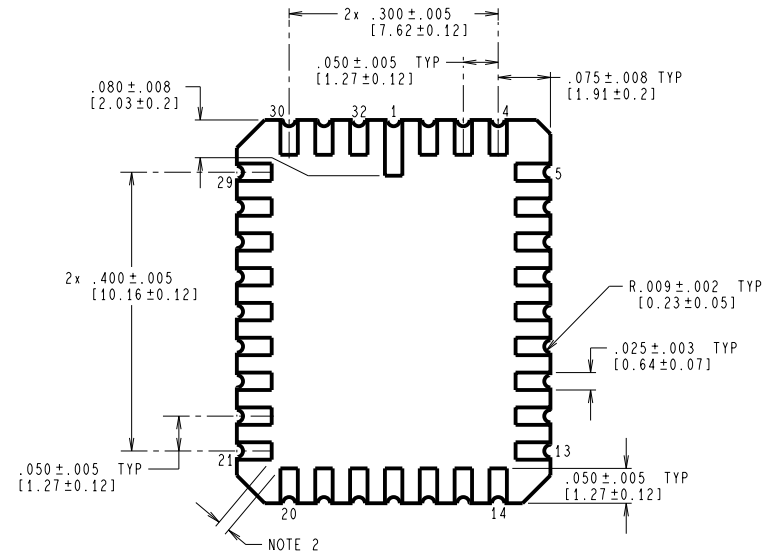
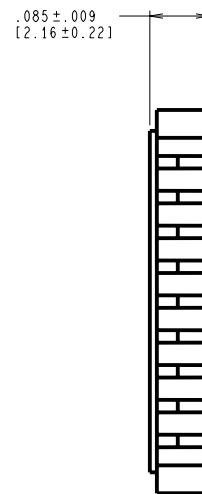
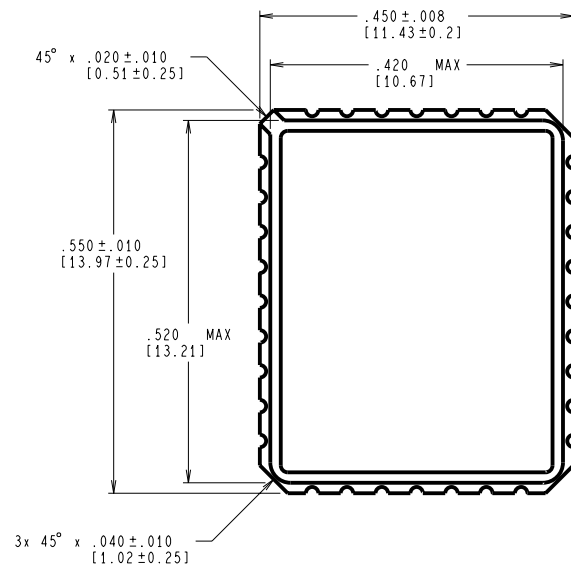


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
B	REVISE AND REDRAW PER NEW STANDARD.	10238	02/27/94	DEG/



NOTES: UNLESS OTHERWISE SPECIFIED.

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - a. 50 MICROINCHES/12.7 MICROMETERS MINIMUM GOLD PLATING
OVER 50-350 MICROINCHES/1.27-8.89 MICROMETERS NICKEL.
 - b. SOLDER DIP.
SOLDER THICKNESS PER LATEST REVISION OF MIL-STD-1835.
2. CORNER PADS MAY HAVE A 45°X.020IN/0.51mm MAXIMUM CHAMFER
TO ACCOMPLISH THE .015IN/0.38mm DIMENSION.
4. REFERENCE JEDEC REGISTRATION MO-041, VARIATION AB, DATED 8/86.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL-M-38510 CONFIGURATION CONTROL

APPROVALS		DATE	NATIONAL SEMICONDUCTOR CORPORATION			
DRAWN <i>Dwayne Grady</i>		02/27/94	2900 Semiconductor Drive, Santa Clara, CA 95052-8090			
DFTG. CHK.			LEADLESS CHIP CARRIER, TYPE C, 32 TERMINAL			
ENGR. CHK.						
APPROVAL						
 PROJECTION 			SCALE N/A	SIZE C	DRAWING NUMBER MKT-E32C	REV B
DO NOT SCALE DRAWING				SHEET 1 of 1		